



Material Content Data Sheet



Sales Product Name		IGU04N60T		Issued		19. July 2018		
MA#		MA001205156						
Package		PG-TO251-3-21		Weight*		352.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.620	0.18	0.18	1759	1759
leadframe	non noble metal	tin	7440-31-5	0.273	0.08		774	
	non noble metal	copper	7440-50-8	181.882	51.55	51.63	515555	516329
wire	non noble metal	aluminium	7429-90-5	0.829	0.24	0.24	2350	2350
encapsulation	organic material	carbon black	1333-86-4	1.919	0.54		5439	
	plastics	epoxy resin	-	21.107	5.98		59830	
	inorganic material	silicondioxide	60676-86-0	104.897	29.73	36.25	297335	362604
leadfinish	non noble metal	tin	7440-31-5	3.976	1.13	1.13	11269	11269
plating	non noble metal	nickel	7440-02-0	0.344	0.10	0.10	976	976
solder	noble metal	silver	7440-22-4	0.019	0.01		55	
	non noble metal	tin	7440-31-5	0.015	0.00		44	
	non noble metal	lead	7439-92-1	0.735	0.21	0.22	2084	2183
heatspreader	non noble metal	iron	7439-89-6	0.036	0.01		103	
	inorganic material	phosphorus	7723-14-0	0.011	0.00		31	
	non noble metal	copper	7440-50-8	36.124	10.24	10.25	102396	102530
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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